NXP USA Inc. - MPC860TCVR66D4 Datasheet



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Applications of **Embedded - Microprocessors**

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	66MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (4), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 95°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mpc860tcvr66d4

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Overview

1 Overview

The MPC860 power quad integrated communications controller (PowerQUICCTM) is a versatile one-chip integrated microprocessor and peripheral combination designed for a variety of controller applications. It particularly excels in communications and networking systems. The PowerQUICC unit is referred to as the MPC860 in this hardware specification.

The MPC860 implements Power ArchitectureTM technology and contains a superset of Freescale's MC68360 quad integrated communications controller (QUICC), referred to here as the QUICC, RISC communications proceessor module (CPM). The CPU on the MPC860 is a 32-bit core built on Power Architecture technology that incorporates memory management units (MMUs) and instruction and data caches.. The CPM from the MC68360 QUICC has been enhanced by the addition of the inter-integrated controller (I²C) channel. The memory controller has been enhanced, enabling the MPC860 to support any type of memory, including high-performance memories and new types of DRAMs. A PCMCIA socket controller supports up to two sockets. A real-time clock has also been integrated.

Table 1 shows the functionality supported by the MPC860 family.

Part	Cache (Cache (Kbytes)		Ethernet			
	Instruction Cache	Data Cache	10T	10/100	АТМ	SCC	Reference ¹
MPC860DE	4	4	Up to 2	_	_	2	1
MPC860DT	4	4	Up to 2	1	Yes	2	1
MPC860DP	16	8	Up to 2	1	Yes	2	1
MPC860EN	4	4	Up to 4	_	_	4	1
MPC860SR	4	4	Up to 4	—	Yes	4	1
MPC860T	4	4	Up to 4	1	Yes	4	1
MPC860P	16	8	Up to 4	1	Yes	4	1
MPC855T	4	4	1	1	Yes	1	2

Table 1. MPC860 Family Functionality

Supporting documentation for these devices refers to the following:

1. MPC860 PowerQUICC Family User's Manual (MPC860UM, Rev. 3)

2. MPC855T User's Manual (MPC855TUM, Rev. 1)



- Up to 8 Kbytes of dual-port RAM
- 16 serial DMA (SDMA) channels
- Three parallel I/O registers with open-drain capability
- Four baud-rate generators (BRGs)
 - Independent (can be tied to any SCC or SMC)
 - Allows changes during operation
 - Autobaud support option
- Four serial communications controllers (SCCs)
 - Ethernet/IEEE 802.3[®] standard optional on SCC1–4, supporting full 10-Mbps operation (available only on specially programmed devices)
 - HDLC/SDLC (all channels supported at 2 Mbps)
 - HDLC bus (implements an HDLC-based local area network (LAN))
 - Asynchronous HDLC to support point-to-point protocol (PPP)
 - AppleTalk
 - Universal asynchronous receiver transmitter (UART)
 - Synchronous UART
 - Serial infrared (IrDA)
 - Binary synchronous communication (BISYNC)
 - Totally transparent (bit streams)
 - Totally transparent (frame-based with optional cyclic redundancy check (CRC))
- Two SMCs (serial management channels)
 - UART
 - Transparent
 - General circuit interface (GCI) controller
 - Can be connected to the time-division multiplexed (TDM) channels
- One SPI (serial peripheral interface)
 - Supports master and slave modes
 - Supports multimaster operation on the same bus
- One I²C (inter-integrated circuit) port
 - Supports master and slave modes
 - Multiple-master environment support
- Time-slot assigner (TSA)
 - Allows SCCs and SMCs to run in multiplexed and/or non-multiplexed operation
 - Supports T1, CEPT, PCM highway, ISDN basic rate, ISDN primary rate, user defined
 - 1- or 8-bit resolution
 - Allows independent transmit and receive routing, frame synchronization, and clocking



Features

- Allows dynamic changes
- Can be internally connected to six serial channels (four SCCs and two SMCs)
- Parallel interface port (PIP)
 - Centronics interface support
 - Supports fast connection between compatible ports on the MPC860 or the MC68360
- PCMCIA interface
 - Master (socket) interface, release 2.1 compliant
 - Supports two independent PCMCIA sockets
 - Supports eight memory or I/O windows
- Low power support
 - Full on-all units fully powered
 - Doze—core functional units disabled except time base decrementer, PLL, memory controller, RTC, and CPM in low-power standby
 - Sleep-all units disabled except RTC and PIT, PLL active for fast wake up
 - Deep sleep—all units disabled including PLL except RTC and PIT
 - Power down mode—all units powered down except PLL, RTC, PIT, time base, and decrementer
- Debug interface
 - Eight comparators: four operate on instruction address, two operate on data address, and two
 operate on data
 - Supports conditions: = $\neq < >$
 - Each watchpoint can generate a break-point internally.
- 3.3-V operation with 5-V TTL compatibility except EXTAL and EXTCLK
- 357-pin ball grid array (BGA) package



NI	Characteristic	33	MHz	40 MHz		50 MHz		66 MHz		- Unit
Num	Characteristic	Min	Мах	Min	Мах	Min	Max	Min	MHz Max 	Unit
B35	A(0:31), BADDR(28:30) to \overline{CS} valid—as requested by control bit BST4 in the corresponding word in UPM	5.58		4.25		3.00	_	1.79		ns
B35a	A(0:31), BADDR(28:30), and D(0:31) to $\overline{\text{BS}}$ valid—as requested by control bit BST1 in the corresponding word in UPM	13.15		10.50	—	8.00	_	5.58		ns
B35b	A(0:31), BADDR(28:30), and D(0:31) to $\overline{\text{BS}}$ valid—as requested by control bit BST2 in the corresponding word in UPM	20.73		16.75	—	13.00	_	9.36		ns
B36	A(0:31), BADDR(28:30), and D(0:31) to GPL valid—as requested by control bit GxT4 in the corresponding word in UPM	5.58		4.25		3.00	_	1.79		ns
B37	UPWAIT valid to CLKOUT falling edge9	6.00		6.00		6.00	_	6.00		ns
B38	CLKOUT falling edge to UPWAIT valid ⁹	1.00	_	1.00	_	1.00		1.00		ns
B39	AS valid to CLKOUT rising edge ¹⁰	7.00		7.00		7.00	_	7.00		ns
B40	A(0:31), TSIZ(0:1), RD/WR, BURST, valid to CLKOUT rising edge	7.00		7.00	_	7.00		7.00	—	ns
B41	$\overline{\text{TS}}$ valid to CLKOUT rising edge (setup time)	7.00		7.00		7.00	_	7.00		ns
B42	CLKOUT rising edge to \overline{TS} valid (hold time)	2.00	_	2.00	_	2.00	_	2.00	_	ns
B43	AS negation to memory controller signals negation	_	TBD	_	TBD	—	TBD	_	TBD	ns

Table 7	Bus O	neration	Timinas	(continued)
	Du3 0	peration	rinnigs	(continucu)

¹ Phase and frequency jitter performance results are only valid if the input jitter is less than the prescribed value.

² If the rate of change of the frequency of EXTAL is slow (that is, it does not jump between the minimum and maximum values in one cycle) or the frequency of the jitter is fast (that is, it does not stay at an extreme value for a long time) then the maximum allowed jitter on EXTAL can be up to 2%.

³ The timings specified in B4 and B5 are based on full strength clock.

⁴ The timing for BR output is relevant when the MPC860 is selected to work with external bus arbiter. The timing for BG output is relevant when the MPC860 is selected to work with internal bus arbiter.

⁵ The timing required for BR input is relevant when the MPC860 is selected to work with internal bus arbiter. The timing for BG input is relevant when the MPC860 is selected to work with external bus arbiter.

⁶ The D(0:31) and DP(0:3) input timings B18 and B19 refer to the rising edge of the CLKOUT in which the TA input signal is asserted.

⁷ The D(0:31) and DP(0:3) input timings B20 and B21 refer to the falling edge of the CLKOUT. This timing is valid only for read accesses controlled by chip-selects under control of the UPM in the memory controller, for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

⁸ The timing B30 refers to \overline{CS} when ACS = 00 and to $\overline{WE}(0:3)$ when CSNT = 0.

⁹ The signal UPWAIT is considered asynchronous to the CLKOUT and synchronized internally. The timings specified in B37 and B38 are specified to enable the freeze of the UPM output signals as described in Figure 18.

¹⁰ The AS signal is considered asynchronous to the CLKOUT. The timing B39 is specified in order to allow the behavior specified in Figure 21.



Figure 9 provides the timing for the input data controlled by the UPM for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

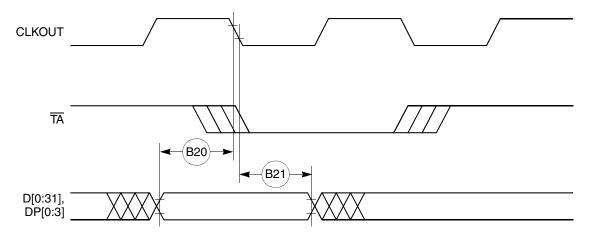
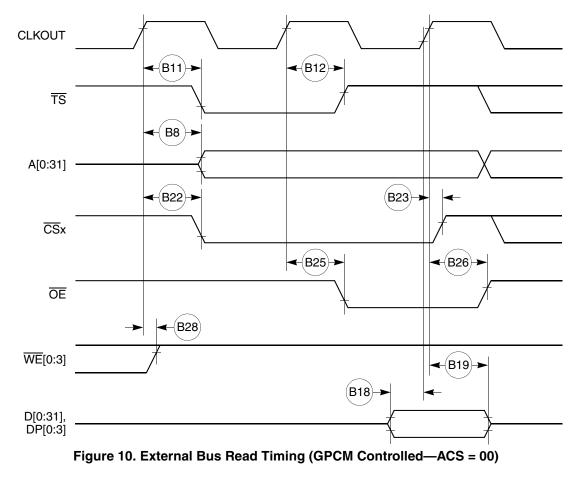


Figure 9. Input Data Timing when Controlled by UPM in the Memory Controller and DLT3 = 1

Figure 10 through Figure 13 provide the timing for the external bus read controlled by various GPCM factors.





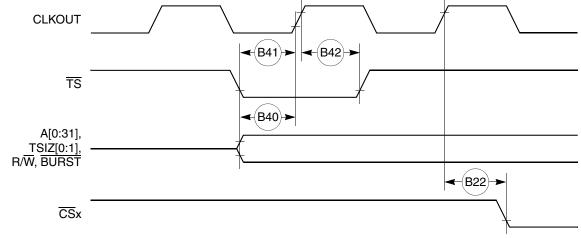


Figure 20 provides the timing for the synchronous external master access controlled by the GPCM.

Figure 20. Synchronous External Master Access Timing (GPCM Handled ACS = 00)

Figure 21 provides the timing for the asynchronous external master memory access controlled by the GPCM.

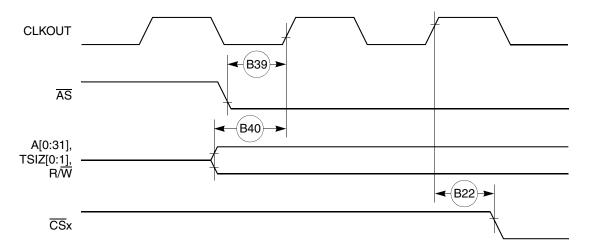




Figure 22 provides the timing for the asynchronous external master control signals negation.

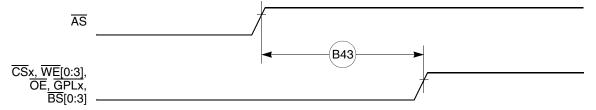


Figure 22. Asynchronous External Master—Control Signals Negation Timing



Table 9 shows the PCMCIA timing for the MPC860.

Table 9. PCMCIA Timing

Num	Characteristic	33	MHz	40 MHz		50 MHz		66 MHz		Unit
Num	Characteristic	Min	Max	Min	Max	Min	Max	Min	Max	Unit
P44	A(0:31), REG valid to PCMCIA Strobe asserted ¹	20.73	—	16.75	—	13.00	—	9.36	—	ns
P45	A(0:31), $\overline{\text{REG}}$ valid to ALE negation ¹	28.30	—	23.00	—	18.00	—	13.15	—	ns
P46	CLKOUT to REG valid	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P47	CLKOUT to REG invalid	8.58	—	7.25	—	6.00	—	4.84	—	ns
P48	CLKOUT to CE1, CE2 asserted	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P49	CLKOUT to $\overline{CE1}$, $\overline{CE2}$ negated	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P50	CLKOUT to PCOE, IORD, PCWE, IOWR assert time	—	11.00		11.00	_	11.00	—	11.00	ns
P51	CLKOUT to PCOE, IORD, PCWE, IOWR negate time	2.00	11.00	2.00	11.00	2.00	11.00	2.00	11.00	ns
P52	CLKOUT to ALE assert time	7.58	15.58	6.25	14.25	5.00	13.00	3.79	10.04	ns
P53	CLKOUT to ALE negate time	—	15.58		14.25		13.00	—	11.84	ns
P54	PCWE, IOWR negated to D(0:31) invalid ¹	5.58	—	4.25	—	3.00	—	1.79	—	ns
P55	${\text{WAITA}} \text{ and } {\text{WAITB}} \text{ valid to CLKOUT rising}$	8.00	—	8.00	—	8.00	—	8.00	—	ns
P56	CLKOUT rising edge to WAITA and WAITB invalid ¹	2.00	_	2.00	_	2.00	_	2.00	_	ns

¹ PSST = 1. Otherwise add PSST times cycle time.

PSHT = 0. Otherwise add PSHT times cycle time.

These synchronous timings define when the WAITx signals are detected in order to freeze (or relieve) the PCMCIA current cycle. The WAITx assertion will be effective only if it is detected 2 cycles before the PSL timer expiration. See Chapter 16, "PCMCIA Interface," in the *MPC860 PowerQUICCTM Family User's Manual*.



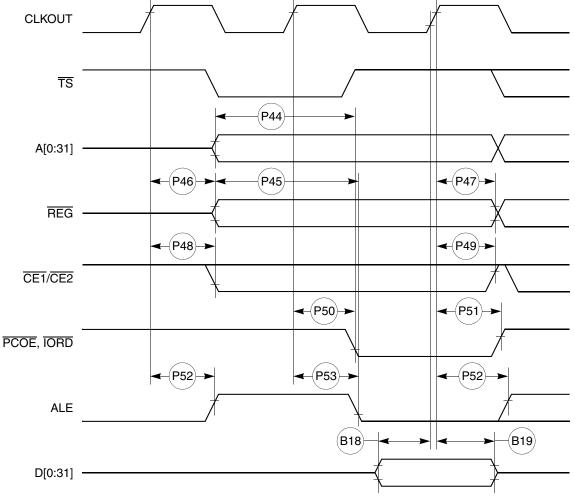


Figure 25 provides the PCMCIA access cycle timing for the external bus read.

Figure 25. PCMCIA Access Cycle Timing External Bus Read



Num	Characteristic	All Freq	Unit	
Nulli	Characteristic	Min	Мах	Unit
42	SDACK assertion delay from clock high	—	12	ns
43	SDACK negation delay from clock low	—	12	ns
44	SDACK negation delay from TA low	—	20	ns
45	SDACK negation delay from clock high	—	15	ns
46	\overline{TA} assertion to rising edge of the clock setup time (applies to external \overline{TA})	7		ns

Table 16. IDMA Controller Timing (continued)

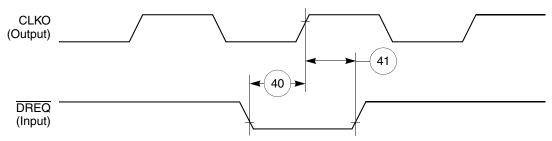


Figure 45. IDMA External Requests Timing Diagram

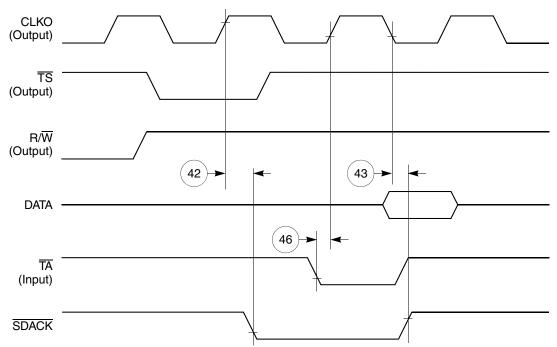


Figure 46. SDACK Timing Diagram—Peripheral Write, Externally-Generated TA



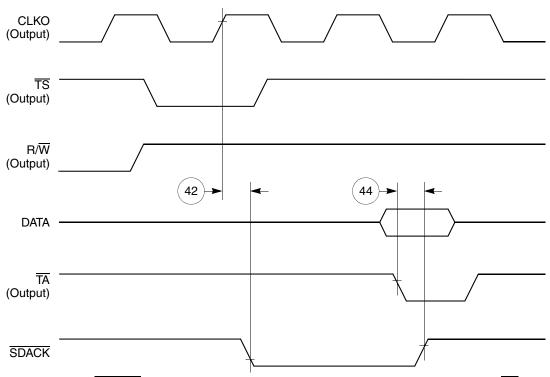


Figure 47. SDACK Timing Diagram—Peripheral Write, Internally-Generated TA

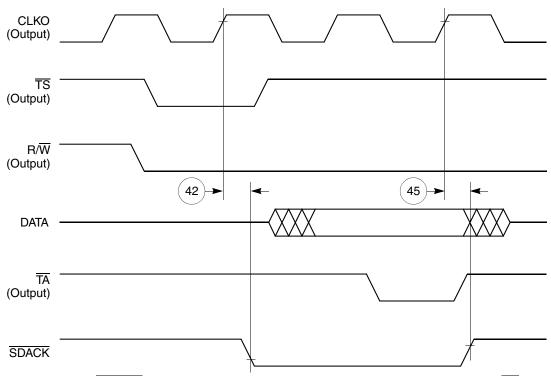


Figure 48. SDACK Timing Diagram—Peripheral Read, Internally-Generated TA



11.4 Baud Rate Generator AC Electrical Specifications

Table 17 provides the baud rate generator timings as shown in Figure 49.

Table 17. Baud Rate Generator Timing

Num	Characteristic	All Freq	Unit	
	Characteristic	Min	Max	Unit
50	BRGO rise and fall time	_	10	ns
51	BRGO duty cycle	40	60	%
52	BRGO cycle	40	_	ns

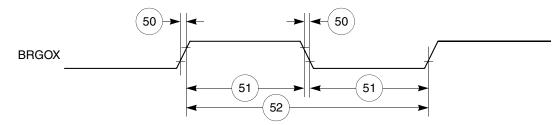


Figure 49. Baud Rate Generator Timing Diagram

11.5 Timer AC Electrical Specifications

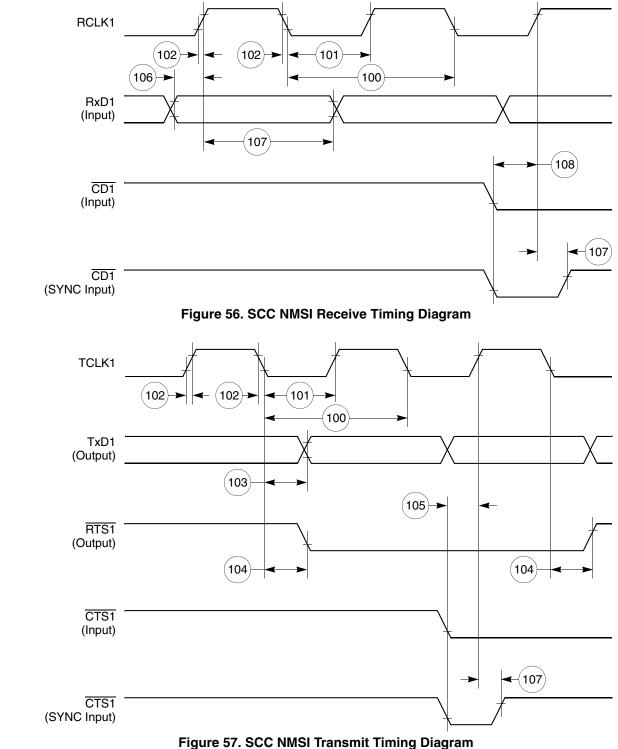
Table 18 provides the general-purpose timer timings as shown in Figure 50.

Table 18. Timer Timing

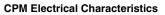
Num		All Freq	Unit	
NUM	Characteristic	Min	Мах	Unit
61	TIN/TGATE rise and fall time	10		ns
62	TIN/TGATE low time	1	_	CLK
63	TIN/TGATE high time	2	—	CLK
64	TIN/TGATE cycle time	3	—	CLK
65	CLKO low to TOUT valid	3	25	ns



Figure 56 through Figure 58 show the NMSI timings.



rigure 57. See NMSF fransline finning Diagram





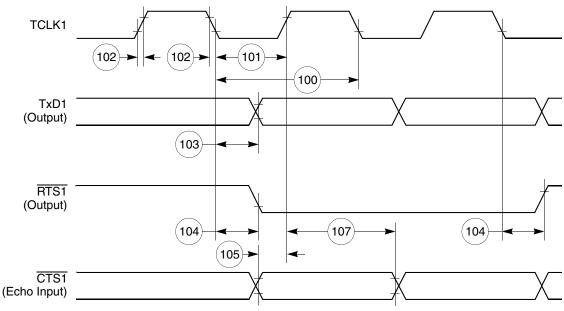


Figure 58. HDLC Bus Timing Diagram

11.8 Ethernet Electrical Specifications

Table 22 provides the Ethernet timings as shown in Figure 59 through Figure 63.

Num	Characteristic	All Freq	uencies	Unit
Num	Characteristic	Min	Max	Unit
120	CLSN width high	40	_	ns
121	RCLK1 rise/fall time	—	15	ns
122	RCLK1 width low	40	—	ns
123	RCLK1 clock period ¹	80	120	ns
124	RXD1 setup time	20	—	ns
125	RXD1 hold time	5	—	ns
126	RENA active delay (from RCLK1 rising edge of the last data bit)	10	—	ns
127	RENA width low	100	—	ns
128	TCLK1 rise/fall time	—	15	ns
129	TCLK1 width low	40	—	ns
130	TCLK1 clock period ¹	99	101	ns
131	TXD1 active delay (from TCLK1 rising edge)	10	50	ns
132	TXD1 inactive delay (from TCLK1 rising edge)	10	50	ns
133	TENA active delay (from TCLK1 rising edge)	10	50	ns
134	TENA inactive delay (from TCLK1 rising edge)	10	50	ns



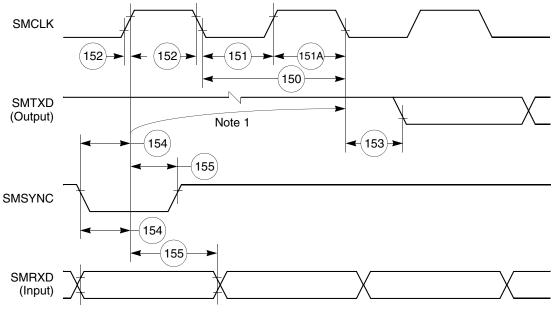
SMC Transparent AC Electrical Specifications 11.9

Table 23 provides the SMC transparent timings as shown in Figure 64.

Table 23. SMC Transparent Timing

Num	Characteristic	All Freq	Unit	
Num	Characteristic	Min	Мах	Unit
150	SMCLK clock period ¹	100	—	ns
151	SMCLK width low	50	—	ns
151A	SMCLK width high	50	—	ns
152	SMCLK rise/fall time	_	15	ns
153	SMTXD active delay (from SMCLK falling edge)	10	50	ns
154	SMRXD/SMSYNC setup time	20	—	ns
155	RXD1/SMSYNC hold time	5	—	ns

¹ SYNCCLK must be at least twice as fast as SMCLK.



Note: 1. This delay is equal to an integer number of character-length clocks.





11.12 I²C AC Electrical Specifications

Table 26 provides the I^2C (SCL < 100 kHz) timings.

Table 26. I²C Timing (SCL < 100 kHz)

Num	Characteristic	All Freq	uencies	Unit
Num		Min	Max	Onit
200	SCL clock frequency (slave)	0	100	kHz
200	SCL clock frequency (master) ¹	1.5	100	kHz
202	Bus free time between transmissions	4.7	_	μS
203	Low period of SCL	4.7	—	μS
204	High period of SCL	4.0	—	μS
205	Start condition setup time	4.7	—	μS
206	Start condition hold time	4.0	—	μS
207	Data hold time	0	—	μS
208	Data setup time	250	—	ns
209	SDL/SCL rise time	—	1	μS
210	SDL/SCL fall time	—	300	ns
211	Stop condition setup time	4.7	—	μS

SCL frequency is given by SCL = BRGCLK_frequency / ((BRG register + 3 × pre_scaler × 2). The ratio SYNCCLK/(BRGCLK/pre_scaler) must be greater than or equal to 4/1.

Table 27 provides the I^2C (SCL > 100 kHz) timings.

Table 27. . I²C Timing (SCL > 100 kHz)

Num	Characteristic	Expression	All Frequencies		Unit
Num		Expression	Min Max		
200	SCL clock frequency (slave)	fSCL	0	BRGCLK/48	Hz
200	SCL clock frequency (master) ¹	fSCL	BRGCLK/16512	BRGCLK/48	Hz
202	Bus free time between transmissions		1/(2.2 * fSCL)	—	s
203	Low period of SCL		1/(2.2 * fSCL)	—	s
204	High period of SCL		1/(2.2 * fSCL)	_	S
205	Start condition setup time		1/(2.2 * fSCL)	—	S
206	Start condition hold time		1/(2.2 * fSCL)	—	S
207	Data hold time		0	_	S
208	Data setup time		1/(40 * fSCL)	_	S
209	SDL/SCL rise time		—	1/(10 * fSCL)	s
210	SDL/SCL fall time		—	1/(33 * fSCL)	S
211	Stop condition setup time		1/2(2.2 * fSCL)		S

SCL frequency is given by SCL = BRGCLK_frequency / ((BRG register + 3) × pre_scaler × 2). The ratio SYNCCLK/(BRGCLK / pre_scaler) must be greater than or equal to 4/1.



13.2 MII Transmit Signal Timing (MII_TXD[3:0], MII_TX_EN, MII_TX_ER, MII_TX_CLK)

The transmitter functions correctly up to a MII_TX_CLK maximum frequency of 25 MHz +1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_TX_CLK frequency -1%.

Table 30 provides information on the MII transmit signal timing.

Table 30. M	MII	Transmit	Signal	Timing
-------------	-----	----------	--------	--------

Num	lum Characteristic		Max	Unit
M5	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER invalid	5	_	ns
M6	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER valid	_	25	
M7	MII_TX_CLK pulse width high	35	65%	MII_TX_CLK period
M8	MII_TX_CLK pulse width low	35%	65%	MII_TX_CLK period

Figure 73 shows the MII transmit signal timing diagram.

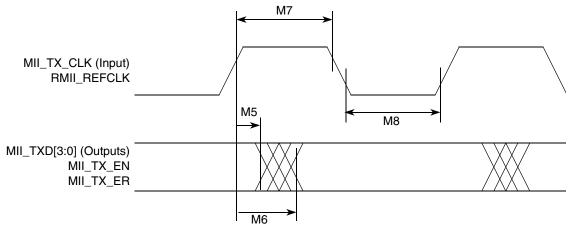


Figure 73. MII Transmit Signal Timing Diagram



Mechanical Data and Ordering Information

Figure 75 shows the MII serial management channel timing diagram.

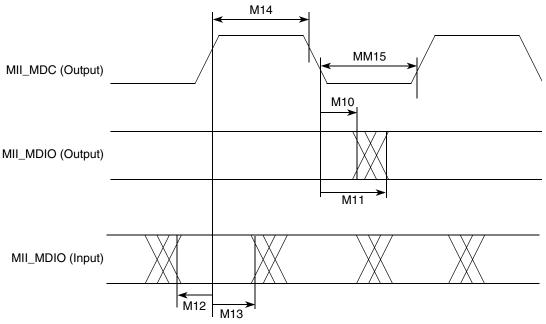


Figure 75. MII Serial Management Channel Timing Diagram

14 Mechanical Data and Ordering Information

14.1 Ordering Information

Table 33 provides information on the MPC860 Revision D.4 derivative devices.

Device	Number of SCCs ¹	Ethernet Support ² (Mbps)	Multichannel HDLC Support	ATM Support
MPC855T	1	10/100	Yes	Yes
MPC860DE	2	10	N/A	N/A
MPC860DT		10/100	Yes	Yes
MPC860DP		10/100	Yes	Yes
MPC860EN	4	10	N/A	N/A
MPC860SR		10	Yes	Yes
MPC860T		10/100	Yes	Yes
MPC860P		10/100	Yes	Yes

Table 33. MPC860 Family Revision D.4 Derivatives

¹ Serial communications controller (SCC)

² Up to 4 channels at 40 MHz or 2 channels at 25 MHz



Table 34 identifies the packages and operating frequencies available for the MPC860.

Package Type	Freq. (MHz) / Temp. (Tj)	Package	Order Number
Ball grid array ZP suffix—leaded ZQ suffix—leaded VR suffix—lead-free	50 0° to 95°C	ZP/ZQ ¹	MPC855TZQ50D4 MPC860DEZQ50D4 MPC860DTZQ50D4 MPC860ENZQ50D4 MPC860SRZQ50D4 MPC860TZQ50D4 MPC860DPZQ50D4 MPC860PZQ50D4
		Tape and Reel	MPC855TZQ50D4R2 MPC860DEZQ50D4R2 MPC860ENZQ50D4R2 MPC860SRZQ50D4R2 MPC860TZQ50D4R2 MPC860DPZQ50D4R2 MPC860DPZQ50D4R2 MPC855TVR50D4R2 MPC860ENVR50D4R2 MPC860SRVR50D4R2 MPC860TVR50D4R2
		VR	MPC855TVR50D4 MPC860DEVR50D4 MPC860DPVR50D4 MPC860DTVR50D4 MPC860ENVR50D4 MPC860PVR50D4 MPC860SRVR50D4 MPC860SRVR50D4 MPC860TVR50D4
	66 0° to 95°C	ZP/ZQ ¹	MPC855TZQ66D4 MPC860DEZQ66D4 MPC860DTZQ66D4 MPC860ENZQ66D4 MPC860SRZQ66D4 MPC860TZQ66D4 MPC860DPZQ66D4 MPC860PZQ66D4
		Tape and Reel	MPC860SRZQ66D4R2 MPC860PZQ66D4R2
		VR	MPC855TVR66D4 MPC860DEVR66D4 MPC860DPVR66D4 MPC860DTVR66D4 MPC860ENVR66D4 MPC860PVR66D4 MPC860SRVR66D4 MPC860TVR66D4

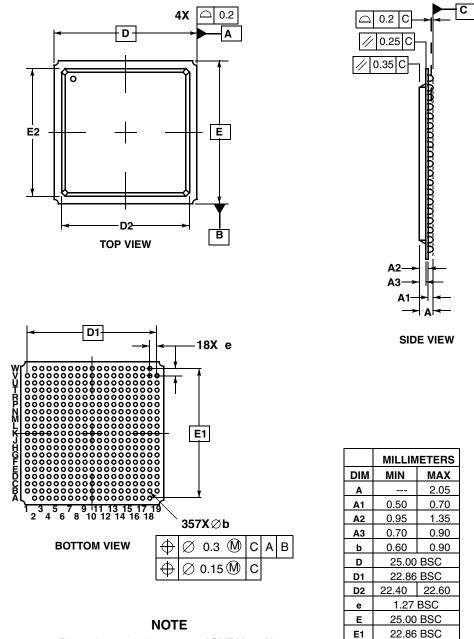
Table 34. MPC860 Family Package/Frequency Availability



Mechanical Data and Ordering Information

14.3 Mechanical Dimensions of the PBGA Package

Figure 77 shows the mechanical dimensions of the ZP PBGA package.



- 1. Dimensions and tolerance per ASME Y14.5M, 1994.
- 2. Dimensions in millimeters.
- 3. Dimension b is the maximum solder ball diameter measured parallel to data C.



22.40

E2

22.60



Document Revision History

15 Document Revision History

Table 35 lists significant changes between revisions of this hardware specification.

Revision	Date	Changes
10	09/2015	In Table 34, moved MPC855TCVR50D4 and MPC855TCVR66D4 under the extended temperature (-40° to 95°C) and removed MC860ENCVR50D4R2 from the normal temperature Tape and Reel.
9	10/2011	Updated orderable part numbers in Table 34, "MPC860 Family Package/Frequency Availability."
8	08/2007	 Updated template. On page 1, added a second paragraph. After Table 2, inserted a new figure showing the undershoot/overshoot voltage (Figure 1) and renumbered the rest of the figures. In Figure 3, changed all reference voltage measurement points from 0.2 and 0.8 V to 50% level. In Table 16, changed num 46 description to read, "TA assertion to rising edge" In Figure 46, changed TA to reflect the rising edge of the clock.
7.0	9/2004	 Added a tablefootnote to Table 6 DC Electrical Specifications about meeting the VIL Max of the I2C Standard Replaced the thermal characteristics in Table 4 by the ZQ package Add the new parts to the Ordering and Availablity Chart in Table 34 Added the mechanical spec of the ZQ package in Figure 78 Removed all of the old revisions from Table 5
6.3	9/2003	Added Section 11.2 on the Port C interrupt pins Nontechnical reformatting
6.2	8/2003	 Changed B28a through B28d and B29d to show that TRLX can be 0 or 1 Changed reference documentation to reflect the Rev 2 MPC860 PowerQUICC Family Users Manual Nontechnical reformatting
6.1	11/2002	 Corrected UTOPIA RXenb* and TXenb* timing values Changed incorrect usage of Vcc to Vdd Corrected dual port RAM to 8 Kbytes
6	10/2002	Added the MPC855T. Corrected Figure 26 on page -36.
5.1	11/2001	Revised template format, removed references to MAC functionality, changed Table 7 B23 max value @ 66 MHz from 2ns to 8ns, added this revision history table

Table 35. Document Revision History